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PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kazutaka Honda	08/21/2013
Tetsuya Enomoto	08/28/2013
Yuuki Nakamura	08/26/2013

RECEIVING PARTY DATA

Name:	Hitachi Chemical Company, Ltd.
Street Address:	9-2, Marunouchi 1-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-6606

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13933230

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NAME OF SUBMITTER:	Bridget D. Burke
Signature:	/bburke/

CH $40.00 13933230

Date:	09/30/2013
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 1 source=13-09-30 Assignment and Declaration#page1.tif	

ASSIGNMENT and DECLARATION under AIA

The undersigned (hereinafter collectively referred to as "ASSIGNOR"), in consideration of the sum of Ten Dollars ($10.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, hereby sells, assigns and transfers to

Hitachi Chemical Company, Ltd.
(Name of Assignee)

(hereinafter referred to as "ASSIGNEE"), of

9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606
JAPAN

the entire right, title and interest for the United States of America as defined in 35 U.S.C. §100, in the invention (hereinafter "INVENTION") entitled:

SEMICONDUCTOR ENCAPSULATION ADHESIVE COMPOSITION, SEMICONDUCTOR ENCAPSULATION FILM-LIKE ADHESIVE, METHOD FOR PRODUCING SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

for which ASSIGNOR has executed an application for United States Patent

☐ on this date (check if Assignment and application are executed on same date)

☑ filed on [July 2, 2013] (check if Assignment is executed after application)
Month/Day/Year

as United States Patent Application No. 13/933,230
(Insert if known)

and all applications on the INVENTION, including any and all divisions, continuations, substitutes and reissues thereof, and all resulting patents on the INVENTION;

ASSIGNOR hereby agrees to testify and to execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection of and title in and to the INVENTION hereby transferred;

ASSIGNOR hereby declares that: (1) the above-identified application was made or authorized by the ASSIGNOR; (2) the ASSIGNOR believes ASSIGNOR to be an original inventor or original joint inventor of the invention claimed in the above-identified application; (3) ASSIGNOR acknowledges that any willful false statement made herein is punishable under 18 U.S.C. 1001 by fine or imprisonment more than five (5) years, or both; and

ASSIGNOR hereby authorizes Joerg-Uwe Szipl and Griffin & Szipl, P.C. to insert in this Assignment any further information necessary or desirable for recordation.

Full Name of the Inventor(s) (Please type)	Signature	Date Signed
(1) Kazutaka Honda	Kazutaka Honda	Aug. 21. 2013
(2) Tetsuya Enomoto	Tetsuya Enomoto	Aug. 28. 2013
(3) Yuuki Nakamura	Yuuki Nakamura	Aug 26, 2013
(4)		
(5)		
(6)		
(7)		

[ ] Check if additional pages are attached.

* For use with non-U.S. inventors.

Revised September 2012